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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

First Inventor: Jiping Li

Title: High Throughput Measurement Of Via Defects In
Interconnects

Serial No.: 10/813,407

Filing Date: March 29, 2004

Examiner: Unknown

Group Art Unit: 2811

Docket No.: BOX016 US

Confirmation No.: 5642

Santa Clara, California
February 25, 2005Commissioner For Patents
P.O. Box 1450
Alexandria, VA 22313-1450**REQUEST FOR STATUS OF APPLICATION**

Sir:

Applicant(s) hereby request(s) a report on the status of the above-identified patent application.

In particular, please advise when this application is expected to be examined.

If a telephone call would expedite this request, please telephone the undersigned attorney at (408) 982-8203.

I hereby certify that this correspondence is being transmitted by facsimile to the U.S. Patent and Trademark Office to the fax number 703-872-9306 on February 25, 2005.



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Respectfully submitted,

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